

REMARKS

Rejections Under 35 USC §102

Claims 51, 52 and 54 have been rejected under 35 USC §102(e) as being anticipated by Nakayama et al. (US Patent 6,621,172).

Claims 51 and 53 have been rejected under 35 USC §102(e) as being anticipated by Horiuchi et al. (US Patent No. 6,731,010).

Allowed Claims

Claims 55-95 have been allowed.

Argument

In order to distinguish from the Nakayama et al. and Horiuchi et al. references, independent claim 51 has been amended to recite the step of "encapsulating the first die in a first encapsulant comprising a planar surface on the first die and at least one feature on the planar surface configured to facilitate bonding to the first encapsulant".

The encapsulating step is shown in Figure 2C. In addition, the first encapsulant 18 (Figure 2C) is shown encapsulating the first die 14. Further, the planar surface 48 (Figure 3C) with the features 46 (Figure 3C) thereon is shown on the die in Figures 1C and 2C.

In Nakayama et al. the anisotropic conductive material 74 (Figure 3) was deemed equivalent to the first encapsulant, and the adhesive 76 (Figure 3) was deemed equivalent to the feature. However, the anisotropic conductive material 74 (Figure 3) does not encapsulate the die 50 (Figure 3), and does not have a surface on the die 50, as presently claimed in amended claim 51. In addition, the adhesive 76 (Figure 3) is not a feature on the surface of the anisotropic conductive material 74 (Figure 3), as presently claimed in amended claim 51.

In Horiuchi et al. the underfill material 37 (Figure 4) was deemed equivalent to the first encapsulant, and the resin 52 (Figure 4) was deemed equivalent to the feature. However, the underfill material 37 does not encapsulate the die 25 (Figure 4), and does not have a surface on the die 25, as presently claimed in amended claim 51. In addition, the resin 52 (Figure 4) is not a feature on the surface of the underfill material 37, as presently claimed in amended claim 51.


The presently claimed method provides an improved component 10 (Figure 2F) because the first encapsulant 18 (Figure 2F) encapsulates the first die 14 (Figure 2F) and provides features 46 (Figure 3F) for bonding a second die 16 (Figure 2D) on the first die 14 (Figure 2F).

Conclusion

In view of the amendments and arguments, favorable consideration and allowance of claims 51-95 is respectfully requested. Should any issues arise that will advance this case to allowance, the Examiner is asked to contact the undersigned by telephone.

DATED THIS 11TH DAY OF July 2005.

Respectfully submitted:



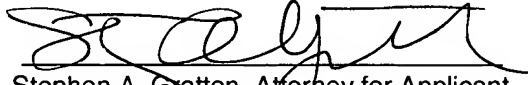
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